

Silicon carbide ceramics bonding compositions.

Publication number: EP0356800

Publication date: 1990-03-07

Inventor: HONGU TATSUHIKO

Applicant: SHINETSU CHEMICAL CO (JP)

Classification:

- International: C04B37/00; C04B37/02; C04B37/00; C04B37/02;
(IPC1-7): C04B37/00; C04B37/02

- European: C04B37/00D2; C04B37/02D2

Application number: EP19890115019 19890814

Priority number(s): JP19880202827 19880815

Also published as:

US4952533 (A1)

EP0356800 (B1)

Cited documents:

DE3311553

GB2137975

DE947056

[Report a data error here](#)

Abstract of EP0356800

A bonding composition for silicon carbide ceramics, comprising powder silicon carbide having a particle size of 1 to 50 μm , powder carbon having a particle size of up to 15 μm , powder silicon having a particle size of up to 10 μm , a thermosetting resin, and a catalytically curable resin and a curing agent therefor is effective in bonding sintered silicon carbide ceramic pieces.

Data supplied from the esp@cenet database - Worldwide

BEST AVAILABLE COPY